

LTM4628-BGA 144LD 15mm X 15mm X 4.92mm (TABLE OF MATERIAL DECLARATION)

The LTM4628-BGA is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2454	Barium Compounds	7727-43-7	0.00736	3.00
				BT/Silica Filler Substances	13776-74-4, 7631-86-9	0.03858	15.72
				Copper Metal	7440-50-8	0.14596	59.47
				Copper Compounds	1328-53-6	0.00006	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00003	0.01
				Gold metal or alloy	7440-57-5	0.00098	0.40
				Nickel	7440-02-0	0.00641	2.61
				Zinc	7440-66-6	0.00034	0.14
				Bisphenol A epoxyresin	25068-38-6	0.00002	0.01
				Continuous Filament Fiber Glass	65997-17-3	0.03034	12.36
				Acrylic Resin	non-disclosure	0.01311	5.34
				Epoxy Resin	non-disclosure	0.00017	0.07
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica amorphous	7631-86-9	0.00008	0.03
				and not containing fibers like talc, asbestos	14807-96-6	0.00079	0.32
				Aromatic carbonyl compounds	non-disclosure	0.00076	0.31
				Cyanoguanidine	461-58-5	0.00002	0.01
				Amine compounds	non-disclosure	0.00010	0.04
				Leveling agent and others	non-disclosure	0.00029	0.12
				Imidazole system curing reagent	non-disclosure	0.00002	0.01
2	Solder Paste	Alloy	0.0022	Sn	7440-31-5	0.00209	95.00
				Sb	7440-36-0	0.00011	5.00
3	Passive/Active Components		0.9673	Iron Powder (Fe)	7439-89-6	0.73159	75.63
				Copper (Cu)	7440-50-8	0.19035	19.68
				Nickel (Ni)	7440-02-0	0.00548	0.57
				Tin (Sn)	7440-31-5	0.00697	0.72
				Ceramic (Ba) Compounds	12047-27-7	0.03291	3.40
4	Solder Ball		0.2419	Sn	7440-31-5	0.23345	96.50
				Ag	7440-22-4	0.00726	3.00
				Cu	7440-50-8	0.00121	0.50
5	Active Ics	Silicon	0.0162	Silicon	7440-21-3	0.01621	100.00
6	Wire	Gold	0.0018	Au	7440-57-5	0.00181	99.99
7	Encapsulation	Epoxy Resin	1.4790	Fused Silica	60676-86-0	1.14176	77.20
				Epoxy Resin	non-disclosure	0.13163	8.90
				Phenol Resin	non-disclosure	0.13163	8.90
				Crytalline Silica	14808-60-7	0.04437	3.00
				Carbon Black	1333-86-4	0.00739	0.50
				Metal Hydroxide	non-disclosure	0.02218	1.50
Total Package Weight			2.9538				

Note1: Composition derived from MSDS and material C of C from Vendors; **Note 2:** Component weight based on assembly of generic parts